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HMM-RLP: A COM-HPC Mini Module

TRIA is extending its large product portfolio of embedded Computer-on-Modules by introducing the HMM-RLP, a COM-HPC Mini module based on the 13th Gen Intel® Core™ processor at embedded world 2025.

COM-HPC Mini offers the advantage of integrating high-performant processors with a high degree of IO connectivity and bandwidth on a small embedded form factor.

Partner Link:

<https://www.tria-technologies.com/com-hpc/>
<https://www.tria-technologies.com/>

Partner Name

TRIA

Solution Name

HMM-RLP COM-HPC
Mini Module

Booth Location

Hall 3A
Booth #3A-225

